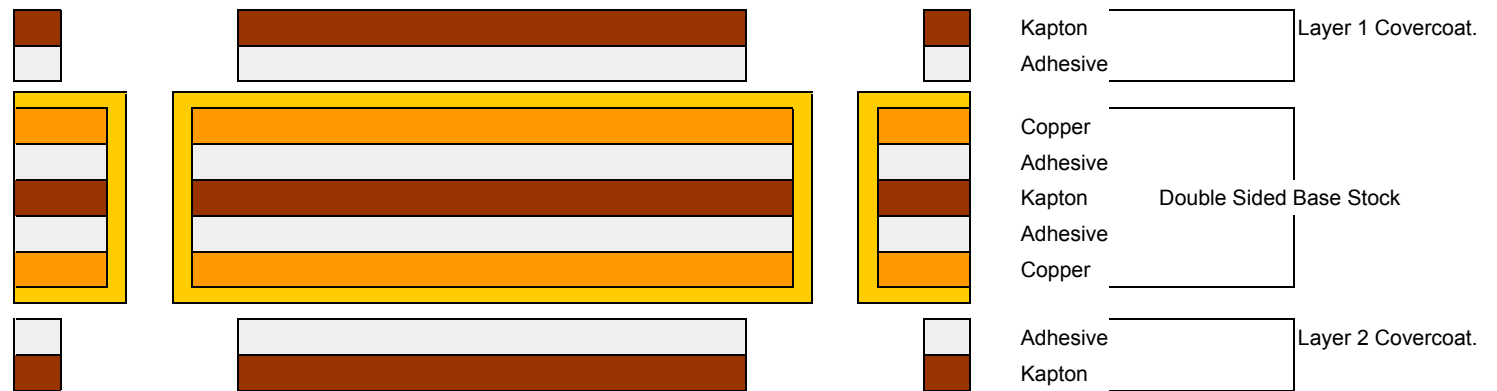






Typical Material Stack up for Double-Sided Flex Circuits (Conventional Adhesive Construction) -Pattern Plated-

The Pattern Plate Process provides the through hole connection
as well as increasing the base copper thickness.



Note: Adhesive or Adhesiveless
Base Stocks may be used.
Individual material layer thicknesses
may be adjusted as required.

Material Legend

-  Copper; Separately per IPC-4562/7 or as Clad Base Stock per IPC-4204/1 or IPC-4204/11
-  Adhesive; Separately per IPC 4203/18 or coated onto one or two sides of Kapton per IPC-4203/1
-  Kapton; Coated with Adhesive per IPC-4203/1 or Adhesiveless Base Stock Core per IPC-4204/11
-  Copper Plating; IPC-6013 / MIL-P-50884